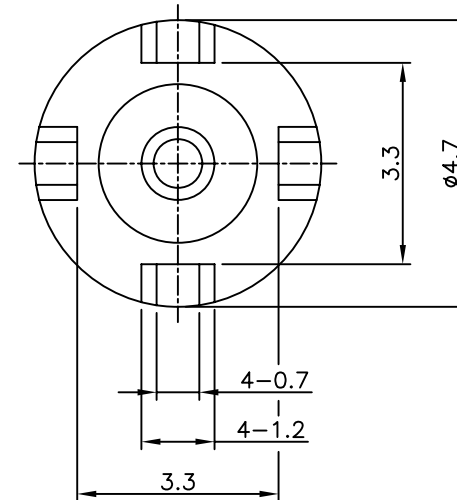
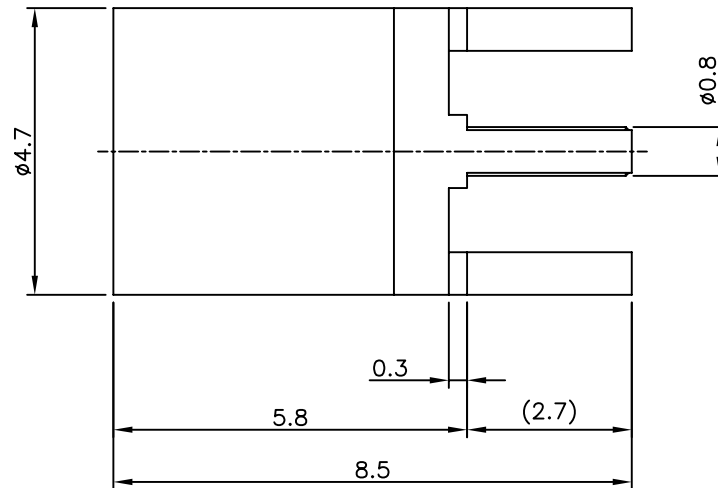
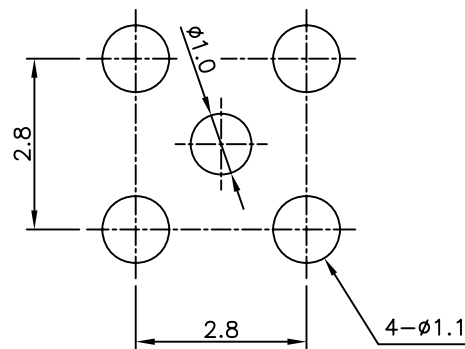


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.12.26.



- ※ COC / 자체 성적서 / 원재료 성적서 / 도금 성적서 포함할 것
- ※ 도금성적서 - ①,② 도금 측정 Point 부품 도면에 기재
- 일반 후레시 도금 spec : $0.03\mu\text{m}$ min



PCB MOUNTING HOLE

5	SPRING RING	1	BeCu C17300	Nickel Plate	DSR00037-5/2
4	CAP	1	MBsBD C3604BD-F	Gold Plate	DCU00038-5/1
3	INSULATOR	1	TEFLON		DIN01782-N/2
2	CONTACT	1	BeCu C17300	Gold Plate	DCT02277-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD04454-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2018. 12. 26.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		TITLE SMF50 PCB JS-4R
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	6/1	A4 DWG NO. CN03811-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	